ABBOCIATION CONNECTINE ELECTRONICS INDUSTRIES® INCLUSTRIES®	kburn, Illinois. A	Il rights reserved u ntions.	nder both	This docume level parts, t	ent is a declar he declaration	ation of the n encompass	substances ses all lowe	within the manu er level materials	facturer listed for which the	d item. N e manufa	Note: if th acturer ha	e item is an as s engineering	sembly with lower responsibility.	
	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Informat						ormation			
Supplier Information														
Company name*	pany name* Company unique ID			Unique ID Authority					Respo	Response Date*				
onsemi	mi				2025-05-15									
Contact Name	act Name Title - Contact				Phone - Contact*				Email	Email - Contact*				
roduct-Env-Stewards Product Enviro Compliance					NA				Prod	Product-Env-Stewards@onsemi.com				
thorized Representative* Title - Representative]	Phone - Representative*				Email	Email - Representative*				
Product-Env-Stewards Product Enviro Compliance			1		NA			Prod	Product-Env-Stewards@onsemi.com					
Requester Item Number Mfr I	em Number	Mfr Item Name			Effective Date Version Manufacturing Si		ite	Weight*		UOM	Unit Type			
74AC	ACT14MTCX HEX SCHMI		T TRIGGER		2025-05-15			PH4		54.823	3	mg	Each	
Manufacturing Proccess Information		1				1	1			•		1		
Terminal Plating / Grid Array Material	Terminal Base Alloy		-STD-020 MS	L Rating	Peak Pr	Peak Process Body Temperature		re Max Time at Peak Temper		rature	ture Number of Reflow Cycles			
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)	NiPdAu) (no CU Alloy		1		260		С	30	sec	onds	nds 3			
Comments														
evel 1 - maximum time at peak temperature during	soldering is 10-3	0 seconds												
for more information regarding material compositi	n please refer to	page 3												

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted						
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	stislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.496	mg	Supplier	Silicon (Si)	7440-21-3		0.496	mg
Die Attach	0.055	mg		Epoxy resin	proprietary data		0.0055	mg
			Supplier	Silver (Ag)	7440-22-4		0.044	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.0055	mg
Lead Frame 21.	21.563	mg	Supplier	Zinc (Zn)	7440-66-6		0.0259	mg
			Supplier	Iron (Fe)	7439-89-6		0.5067	mg
			Supplier	Copper (Cu)	7440-50-8		21.0239	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0065	mg
Mold Compound-Black	32.2	mg		Epoxy resin	proprietary data		1.61	mg
			Supplier	Phenolic Resin	Proprietary Data		0.644	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.805	mg
			Supplier	Carbon Black (C)	1333-86-4		0.161	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		28.98	mg
Plating	0.161	mg	Supplier	Palladium (Pd)	7440-05-3		0.005	mg
			В	Nickel (Ni)	7440-02-0		0.153	mg
			Supplier	Gold (Au)	7440-57-5		0.003	mg
Wire Bond - Au	0.348	mg	Supplier	Gold (Au)	7440-57-5		0.348	mg